



Application Data Sheet

Application Information

Application number::	<u>10618933</u>
Filing Date::	<u>07/14/03</u>
Application Type::	Regular
Subject Matter::	Utility
Title::	Semiconductor multipackage module including processor and memory package assemblies
Attorney Docket Number::	CPAC 1041-2
Suggested Drawing Figure::	
Total Drawing Sheets::	
Small Entity?::	No

Applicant Information

Applicant Authority Type:	Inventor
Primary Citizenship Country:	US
Status:	Full Capacity
Given Name:	Marcos
Family Name:	Karnezos
City of Residence:	Palo Alto
State or Province of Residence:	CA
Country of Residence:	US
Street of mailing address:	535 Lytton Avenue
City of mailing address:	Palo Alto
State or Province of mailing address:	CA
Country of mailing address:	US
Postal or Zip Code of mailing address:	94301

Correspondence Information

Correspondence Customer Number:: 22470

Representative Information

Representative Customer Number::	22470	
----------------------------------	-------	--

Domestic Priority Information

Application::	Continuity Type::	Parent Application::	Parent Filing Date::
This application	An application claiming the benefit under 35 USC 119 (e)	60460541	June <u>April</u> 4, 2003

Assignee Information

Assignee name:: ChipPAC, Inc
Street of mailing address:: 47400 Kato Road
City of mailing address:: Fremont
State or Province of mailing address:: CA
Country of mailing address:: US
Postal or Zip Code of mailing address:: 94538